

overdriving the main chuck toward the probe card while measuring a load applied to the object of inspection by contact with the probes and controlling the movement of the main chuck in accordance with the measured load; and

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inspecting electrical properties of the object of inspection by means of the probes, wherein said measurement of the load applied to the object of inspection by contact with the probes includes steps of locating a polishing mechanism right under the probes, the polishing mechanism including a polish plate to be used to polish the tip of the probes; moving the located polishing mechanism toward the probe card, thereby bringing the polish plate into contact with the probes; overdriving the polishing mechanism toward the probe card; and measuring a load applied to the polish plate by the probes by means of a pressure sensor located under the polishing mechanism during the overdrive operation.

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6. (Once Amended) A probing method comprising steps of:

moving a main chuck in X-, Y-, and θ -directions to align an object of inspection on the main chuck with probes of a probe card located over the main chuck;

moving the main chuck in a Z-direction, thereby bringing electrodes of the object of inspection into contact with the probes;

overdriving the main chuck toward the probe card while measuring a load applied the object of inspection by contact with the probes by means of a sensor and controlling the movement of the main chuck in accordance with the measured load; and

inspecting electrical properties of the object of inspection by means of the probes, wherein said sensor is located on at least one of the lower part of the main chuck and between an LM guide and an XY-stage on which the main chuck is set.
